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Responsible committee: EPL/501 Electronic Assembly Technology

Interested committees:

Title: BS EN IEC 61189-3-720 Test methods for electrical materials, printed boards and other interconnection structures and assemblies

Part 3-720: Test methods for interconnection structures (circuit boards) - Transmission loss test method for high frequency multilayer circuit boards

Please notify the secretary if you are aware of any keywords that might assist in classifying or identifying the standard or if the content of this standard

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- ii) affects other national standard(s)
- iii) requires additional national guidance or information

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Introduction

This draft standard is based on national and international discussions. Your comments on this draft are invited and will assist in the preparation of the consequent standard.

For international standards, comments will be reviewed by the relevant UK national committee before sending the consensus UK vote and comments to the international committee, which will then decide appropriate action. If the international standard is approved, it is usual for the text to be published as a British Standard.

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Please indicate whether you consider the UK should submit a negative (with supporting technical reasons) or positive vote on this draft. Please indicate if you are aware of any reason why this draft standard should not be published as a British Standard.

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Template for comments and secretariat observations

Date: xx/xx/20xx	Document: ISO/DIS xxxx
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1	2	(3)	4	5	(6)	7
MB	Clause No./ Subclause No./Annex (e.g. 3.1)	Paragraph/Figure/ Table/Note	Type of comment	Commend (justification for change) by the MB	Proposed change by the MB	Secretariat observations on each comment submitted
	3.1	Definition 1	ed	Definition is ambiguous and needs clarifying.	Amend to read '...so that the mains connector to which no connection...'	
	6.4	Paragraph 2	te	The use of the UV photometer as an alternative cannot be supported as serious problems have been encountered in its use in the UK.	Delete reference to UV photometer.	



91/2013/CD

COMMITTEE DRAFT (CD)

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IEC TC 91 : ELECTRONICS ASSEMBLY TECHNOLOGY	
SECRETARIAT: Japan	SECRETARY: Mr Osamu IKEDA
OF INTEREST TO THE FOLLOWING COMMITTEES:	HORIZONTAL FUNCTION(S):
ASPECTS CONCERNED:	

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TITLE:
Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 3-720: Test methods for interconnection structures (circuit boards) - Transmission loss test method for high frequency multilayer circuit boards

NOTE FROM TC/SC OFFICERS:

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARDS AND
OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –****PART 3-720: TEST METHODS FOR INTERCONNECTION STRUCTURES
(CIRCUIT BOARDS) –****TRANSMISSION LOSS TEST METHOD FOR HIGH FREQUENCY
MULTILAYER CIRCUIT BOARDS**

FOREWORD

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IEC 6XXXX has been prepared by subcommittee XX: TITLE, of IEC technical committee XX: TITLE. It is [...an International Standard, a Technical Specification: specify document type...].

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available

94 at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are
95 described in greater detail at www.iec.ch/publications.

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- 99 • reconfirmed,
- 100 • withdrawn,
- 101 • replaced by a revised edition, or
- 102 • amended.

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